Abstracts

RF-microwave multi-layer integrated passives using fully organic System on Package (SOP) technology

M.F. Davis, A. Sutono, K. Lim, J. Laskar, V. Sundaram, J. Hobbs, G.E. White and R. Tummala. "RF-microwave multi-layer integrated passives using fully organic System on Package (SOP) technology." 2001 MTT-S International Microwave Symposium Digest 01.3 (2001 Vol. III [MWSYM]): 1731-1734 vol.3.

This paper presents high-density, fully organic multi-layer interconnects and integrated passives for RF and microwave System on Package (SOP) development. The components developed in this technology include novel CPW-microstrip transitions, high Q passives, as well as a planar antenna on a package. High Q passives, designed to be implemented using the featured CPW-microstrip transitions in this organic multi-layer technology, demonstrate the feasibility of implementing SOP technology for RF and microwave applications. This technology also employs a lifted slot antenna with vertical feed to reduce loss at the feeding point and to minimize pattern distortion.

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